DSK9J01

Silicon N-channel Junction FET

For low frequency amplification For pyroelectric sensor DSK5J01 in SSMini3 type package

■ Features

- High gate-drain voltage (source open) V_{GDO}
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Gate-drain breakdown voltage	V _{GDS}	-55	V
Drain current	I_D	30	mA
Gate current	I_G	10	mA
Power dissipation	P_{D}	125	mW
Channel temperature	T _{ch}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

■ Package

• Code

SSMini3-F3-B

- Pin Name
 - 1: Source
 - 2: Drain
 - 3: Gate

■ Marking Symbol: B6

■ Electrical Characteristics $T_a = 25$ °C±3°C

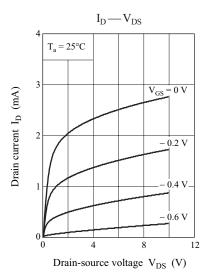
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Gate-drain breakdown voltage	V_{GDS}	$I_G = -100 \mu\text{A}, V_{DS} = 0$	-55			V
Drain-source cutoff current *	I_{DSS}	$V_{DS} = 10 \text{ V}, V_{GS} = 0$	1.0		6.5	mA
Gate-source cutoff current	I_{GSS}	$V_{GS} = -30 \text{ V}, V_{DS} = 0$			-10	nA
Gate-source cutoff voltage	V _{GSC}	$V_{DS} = 10 \text{ V}, I_D = 10 \mu\text{A}$			-5	V
Forward transfer admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 5 \text{ mA}, f = 1 \text{ MHz}$	2.5	7.5		mS
Short-circuit input capacitance (Common source)	C _{iss}	V -103/V -0.5-1 MIL		6.0		pF
Reverse transfer capacitance (Common source)	C _{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		2.5		pF

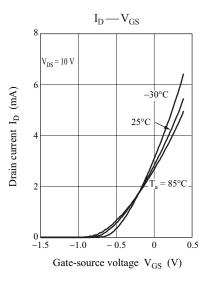
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

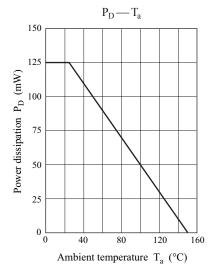
2. *: Rank classification

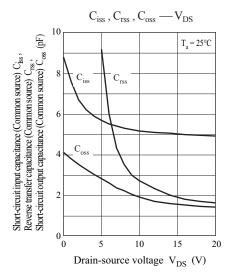
Code	Р	Q	
Rank	Р	Q	
I_{DSS}	1.0 to 3.0	2.0 to 6.5	
Marking Symbol	B6P	B6Q	

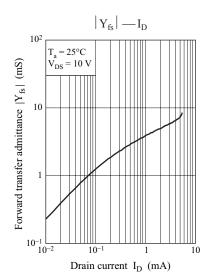
DSK9J01 Panasonic







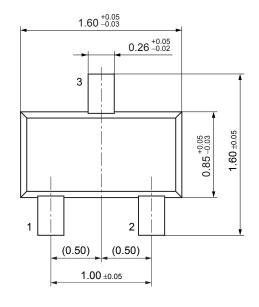


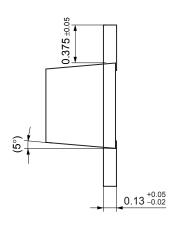


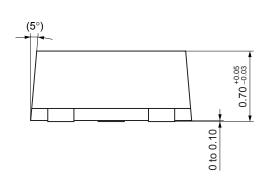
2 Ver. AED

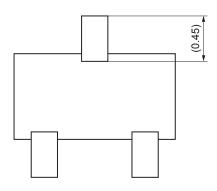
SSMini3-F3-B

Unit: mm









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